

RCD100N19

Nch 190V 10A Power MOSFET

V_{DSS}	190V
R _{DS(on)} (Max.)	182m Ω
I _D	10A
P_D	85W

Features

- 1) Low voltage drive (4V drive).
- 2) Low on-resistance.
- 3) Fast switching speed.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.
- 6) Pb-free lead plating; RoHS compliant
- 7) 100% Avalanche tested

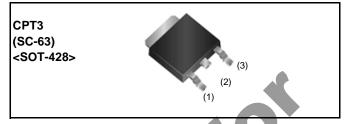
Application

Switching Power Supply

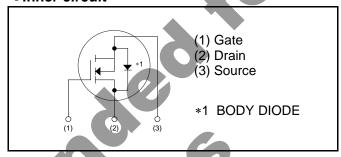
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	C10N19

• Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter		Symbol	Value	Unit
Drain - Source voltage		V_{DSS}	190	V
Continuous drain current	$T_c = 25^{\circ}C$	I _D *1	±10	А
Continuous diain current	I _D *1	±5.4	А	
Pulsed drain current	I _{D,pulse} *2	±40	А	
Gate - Source voltage		V_{GSS}	±20	V
Avalanche energy, single pulse		E _{AS} *3	8.33	mJ
Avalanche current		I _{AR} *3	5.0	А
Power dissipation	$T_c = 25^{\circ}C$	P _D	85	W
rower dissipation	$T_a = 25^{\circ}C^{*4}$	P _D	0.85	W
Junction temperature		T _j	150	°C
Range of storage temperature		T _{stg}	−55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.46	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

• Electrical characteristics ($T_a = 25$ °C)

Davamatas	Cumbal		Values			l lmit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	190	-	-	V
Zoro gato voltago drain current	L	$V_{DS} = 190V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	-	3	10	^
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 190V, V_{GS} = 0V$ $T_j = 125^{\circ}C$		-	100	μΑ
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	·	-	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	0.5	-	2.5	V
		$V_{GS} = 10V, I_D = 5.0A$	-	130	182	
Static drain - source	*5	$V_{GS} = 4.0V, I_D = 5.0A$	-	136	190	O
on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 5.0A$ $T_1 = 125^{\circ}C$	-	195	275	mΩ
Forward transfer admittance	9 _{fs}	$V_{DS} = 10V, I_{D} = 5.0A$	6	12	-	S



●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	2000	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	95	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	60		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 100 V$, $V_{GS} = 10 V$	-	15		
Rise time	t _r *5	I _D = 5.0A	-	20	-	no
Turn - off delay time	t _{d(off)} *5	$R_L = 20\Omega$	-	140	-	ns
Fall time	t _f *5	$R_G = 10\Omega$		75	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
raiailletei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 100V	C	52	-	
Gate - Source charge	Q _{gs} *5	I _D = 10A	·	5	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	11	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \approx 100V, I_D = 10A$	-	2.5	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol Conditions -			Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	l _s *1	T _c = 25°C	ı	ı	10	Α
Pulsed source current	I _{SM} *2	1 _c = 25 C	1	1	40	Α
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0V, I_{S} = 10A$	-	1	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 5.0A	-	95	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	255	-	nC

^{*1} Limited only by maximum temperature allowed.

*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Mounted on a epoxy PCB FR4 (20mm × 30mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

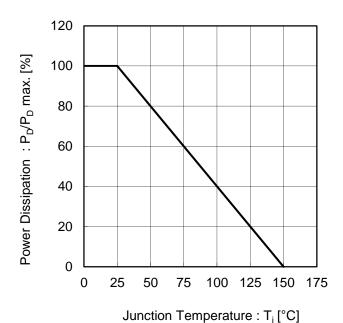
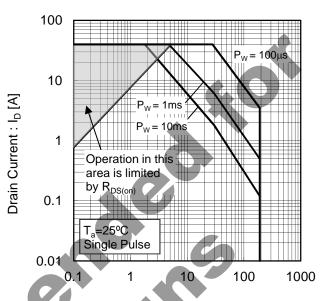
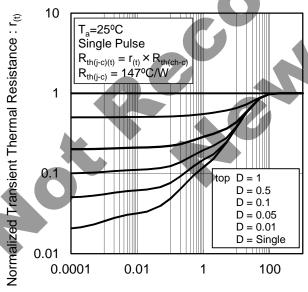


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

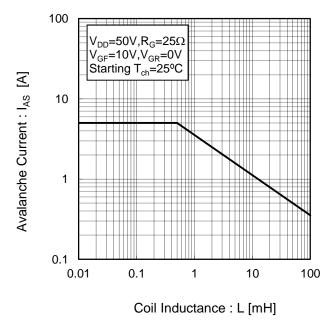
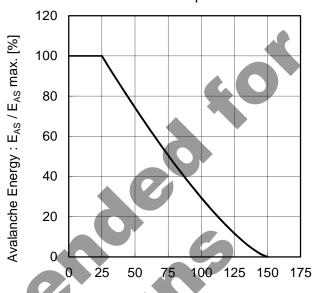
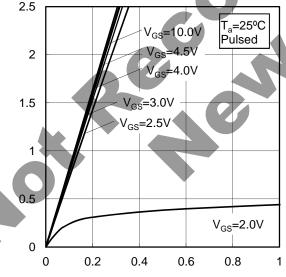


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



Junction Temperature : T_i [°C]

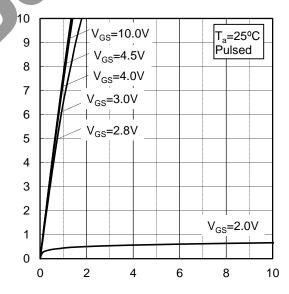
Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

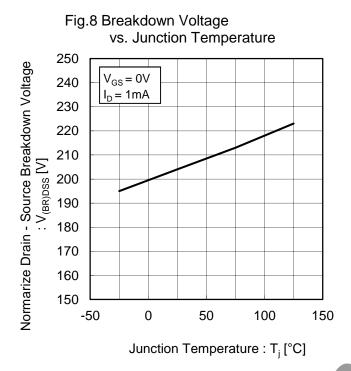
Drain Current : I_D [A]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]



100
V_{DS}= 10V

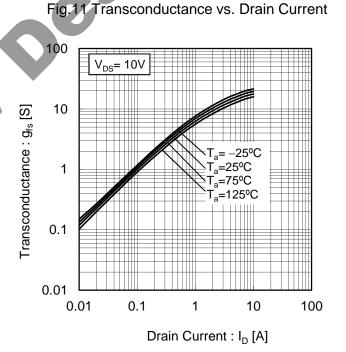
10
T_a= 125°C
T_a= 75°C
T_a= 25°C
T_a= -25°C

0.001
0.001
0.001
0.001
0.001

Fig.9 Typical Transfer Characteristics

Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature 3.0 $V_{DS} = 10V$ Gate Threshold Voltage: V_{GS(th)} [V] 2.5 $I_D = 1 \text{mA}$ 2.0 1.5 1.0 0.5 75 100 125 150 -50 -25 50 0 25 Junction Temperature : T_i [°C]



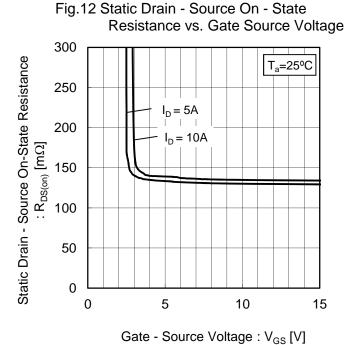
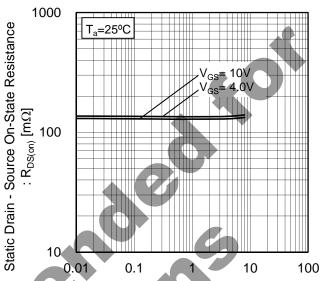
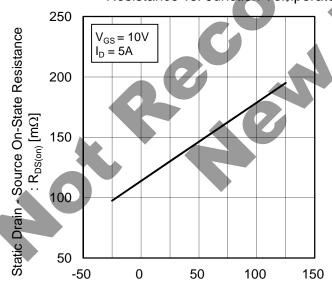


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)



Drain Current : I_D [A]

Fig.14 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

10 0.01

• Electrical characteristic curves

Resistance vs. Drain Current(II) 1000 Static Drain - Source On-State Resistance $V_{GS} = 10V$ =75°C -25°C $: R_{\mathsf{DS}(\mathsf{on})} \ [\mathsf{m}\Omega]$ 100

Fig.15 Static Drain - Source On - State

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

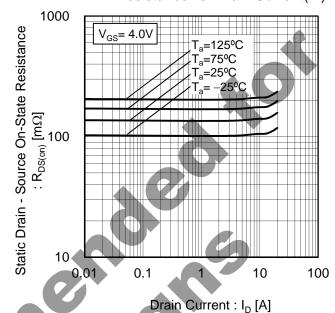


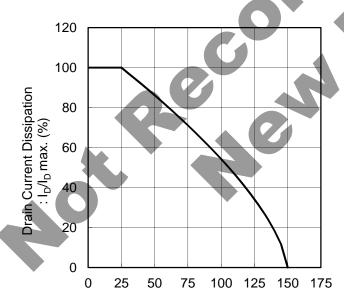
Fig.17 Drain Current Derating Curve

1

Drain Current : I_D [A]

10

0.1



Junction Temperature : T_i [°C]

100

Fig.18 Typical Capacitance

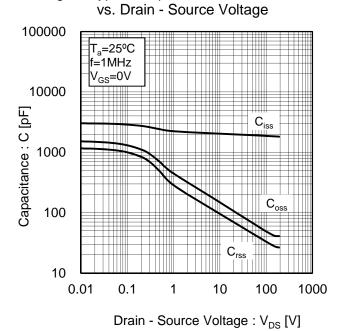
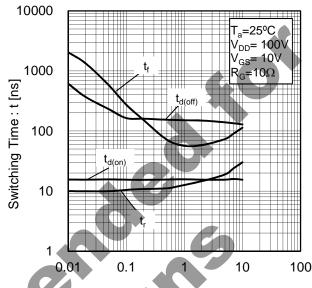
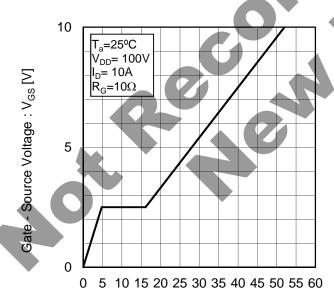


Fig.19 Switching Characteristics

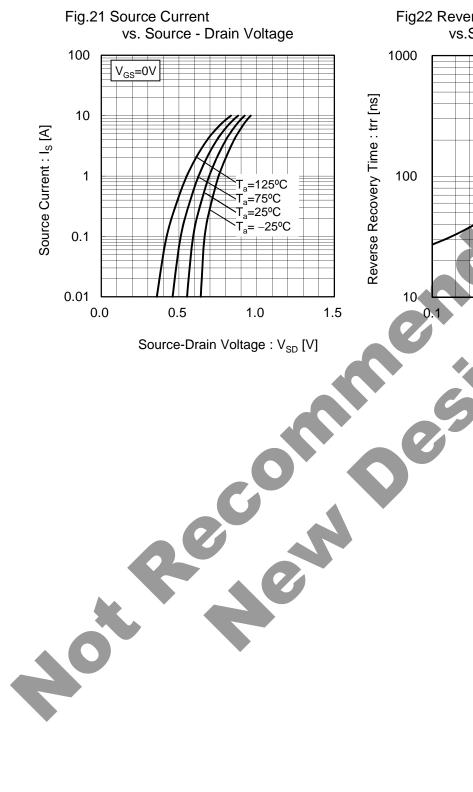


Drain Current : I_D [A]

Fig.20 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]



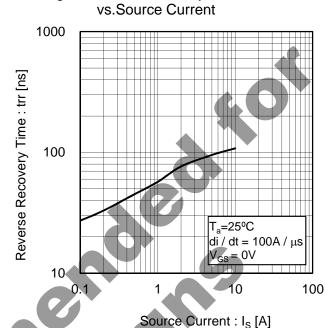


Fig22 Reverse Recovery Time

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

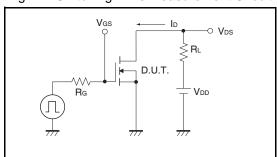


Fig.2-1 Gate Charge Measurement Circuit

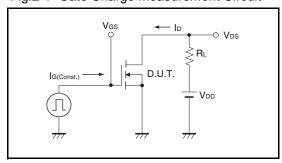


Fig.3-1 Avalanche Measurement Circuit

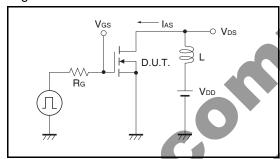


Fig.1-2 Switching Waveforms

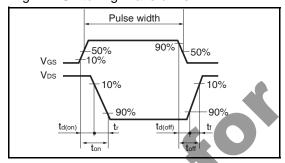


Fig.2-2 Gate Charge Waveform

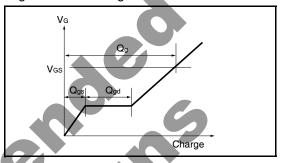
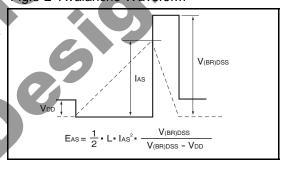
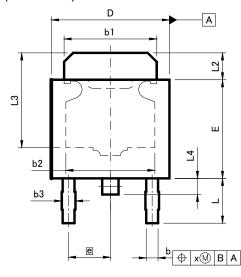


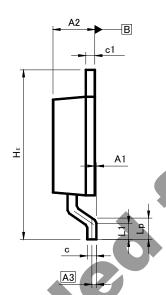
Fig.3-2 Avalanche Waveform

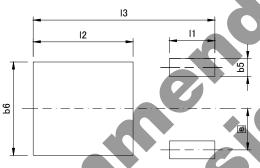


●Dimensions (Unit : mm)









DIM	MILIM	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
A1	0.00	0.15	0	0.006
A2	2.20	2.50	0.087	0.098
A3	0.2	25	0.0	01
b	0.55	0.75	0.022	0.03
b1	5.00	5.30	0.197	0.209
b2	5.0	00	0.3	20
b3	0.	75	0.0	03
o	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
E	5.40	5.80	0.213	0.228
е	2.3	30	0.09	
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.11
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.3	30	0.209	
L4	0.9	0.90		35
Lp	1.00	1.60	0.039	0.063
х		0.25		0.01

DIM MILIME		ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.00	-	0.04
b6	-	5.20	1	0.205
l1	_	2.50	-	0.098
12	_	5.50	-	0.217
13	-	10.00	-	0.394

Dimension in mm/inches

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CLASSIV	CLASSIII	CLASSⅢ	CLASSII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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